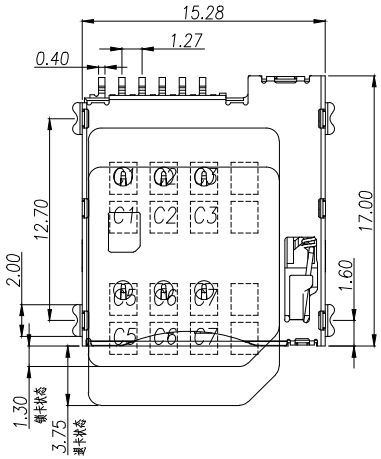
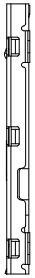
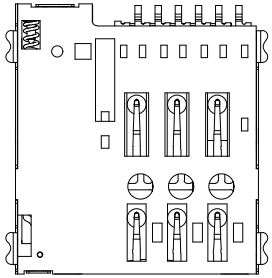
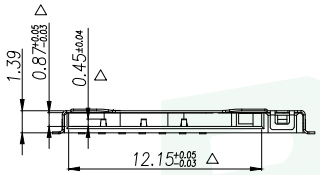
REV.	DESCRIPTION	ECN NO.	NAME	DATE

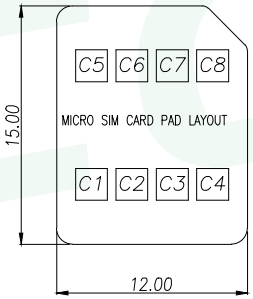


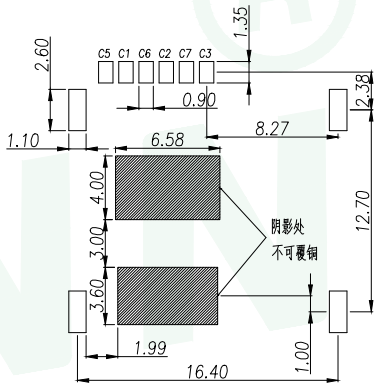




1,MATERIAL:
HOUSING:LCP S475 UL 94V-0
CONTACT:C5191
SHELL:SUS304-H
2,FINISH:
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,
3,ELECTRICAL CHARACTERISTICS
RATING CURRENT : 0.5A MAX.
CONTACT RESISTANCE :50 mΩ MAX
DIELECTRIC WITHSTANDING : 500V AC MIN.
INSULATION RESISTANCE: 1000 MΩ MIN.
4,MECHANICAL CHARACTERISTICS
MATING CYCLE :3000 CYCLES







RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)

RECOMMENDED MATAL MASK T=0.12mm

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				BXCONN®
DIM. TOL. X X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 GENERAL ANGLE: ±3°	TITLE: 1.35H 6PIN PUSH PUSH MICRO SIM CARD CONNECTOR				
	DWG. NO.: SIM203-TZ6P			DRAWN: MAX	
	PART NO.: SIM203-TZ6P			CHECKED: ELLA	
	UNIT: mm	SCALE: none	SHEET: 1of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL